NXP

Final Product Change Notification	201510016F01

Issue Date: 01-Dec-2015
Effective Date: 15-Mar-2016

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QUALITY

Management Summary

Release of UTAC as additional production site and change to improved leadframe in production for SOT1176 at NXP assembly center APB (Bangkok, Thailand)

Change Category

[ ] Wafer Fab process [X] Assembly Process [ ] Product Marking   [X] Design
[ ] Wafer Fab materials   [X] Assembly Materials   [ ] Electrical spec./Test coverage   [ ] Mechanical Specification
[ ] Wafer Fab location [X] Assembly Location   [X] Test Location   [ ] Packing/Shipping/Labeling

Introduction of UTAC as second source for SOT1176 and change to improved LF @ APB

Details of this Change

UTAC is an already released supplier for NXP Semiconductors.
Products in the package SOT1176 are running in production at APB and are planned at UTAC as additional source.
Change to improved leadframe for SOT1176 in our NXP assembly center APB (Bangkok, Thailand).
Leadframe design is improved to increase mechanical robustness (see also self-qualification report).

New leadframe design will be used in both sites

Why do we Implement this Change

- Increase of production capacity and flexibility.
- Increase of mechanical robustness

Identification of Affected Products

Top side marking & labels on reels & plano boxes.

Product Availability

Sample Information
Samples are available from 30-Nov-2015
Production

Planned first shipment 09-Mar-2016

<div style="background-color:#4472C4; color:white; font-weight:bold; padding:4px;">Impact</div>

No negative impact to form, fit or function.
Data Sheet Revision
No impact to existing datasheet
Disposition of Old Products
Existing inventory will be shipped until depleted

<div style="background-color:#4472C4; color:white; font-weight:bold; padding:4px;">Timing and Logistics</div>

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 31-Dec-2015.

<div style="background-color:#4472C4; color:white; font-weight:bold; padding:4px;">Contact and Support</div>

For all inquiries regarding the ePCN tool application or access issues, please [contact NXP "Global Quality Support Team"](#).

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:
Name   GA Customer Support
e-mail address   DiscrQA.Helpdesk.GAProducts@nxp.com
At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards.
Customer Focus, Passion to Win.

NXP Quality Management Team.

<div style="background-color:#4472C4; color:white; font-weight:bold; padding:4px;">About NXP Semiconductors</div>

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